

CLAIMS

1. An adhesive tape for processing a semiconductor wafer or the like, the adhesive tape comprising:

- 5 a base layer, and
an adhesive layer formed on the base layer, wherein
the adhesive layer comprises a curing component that cures the adhesive layer,
the base layer is composed mainly of a resin into which a polymer-type antistatic agent has been kneaded, and
10 the polymer-type antistatic agent has a melt mass flow rate (MFR), measured under measurement conditions of 190°C and 21.18 N in accordance with JIS K7210, of at least 10.0 g/10 min and not more than 15.0 g/10 min.

2. An adhesive tape for processing a semiconductor wafer or the like, the adhesive tape comprising:

- 15 a base layer, and
an adhesive layer formed on the base layer, wherein
the adhesive layer comprises a curing component that cures the adhesive layer,
the base layer is composed mainly of a resin in which a polymer-type antistatic agent has been dispersed, and
20 the polymer-type antistatic agent has a melt mass flow rate (MFR), measured under measurement conditions of 190°C and 21.18 N in accordance with JIS K7210, of at least 10.0 g/10 min and not more than 15.0 g/10 min.

3. The adhesive tape for processing a semiconductor wafer or the like according to claim 1 or 2, wherein a 1% decay time at an applied voltage of $\pm 5,000$ V is not more than 0.15 seconds.
- 5 4. The adhesive tape for processing a semiconductor wafer or the like according to claim 1 or 2, wherein a melting point of the polymer-type antistatic agent is at least 140°C.
- 10 5. The adhesive tape for processing a semiconductor wafer or the like according to claim 1 or 2, wherein the resin is a mixture of a polypropylene and an elastomer.
6. The adhesive tape for processing a semiconductor wafer or the like according to claim 1 or 2, wherein the resin is a mixture of a polyethylene and an elastomer.
- 15 7. The adhesive tape for processing a semiconductor wafer or the like according to claim 1 or 2, wherein the polymer-type antistatic agent contains not more than 100 ppm of cations and not more than 100 ppm of anions based on a weight of the polymer-type antistatic agent.

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5 a base layer, and

an adhesive layer formed on the base layer, wherein

the adhesive layer comprises a curing component that cures the adhesive layer,

the base layer is composed mainly of a resin into which a polymer-type antistatic agent has been kneaded, and

10 the polymer-type antistatic agent has a melt mass flow rate (MFR), measured under measurement conditions of 190°C and 21.18 N in accordance with JIS K7210, of at least 10.0 g/10 min and not more than 15.0 g/10 min, and wherein the polymer-type antistatic agent contains not more than 100 ppm of cations and not more than 100 ppm of anions based on a weight of the polymer-type antistatic agent.